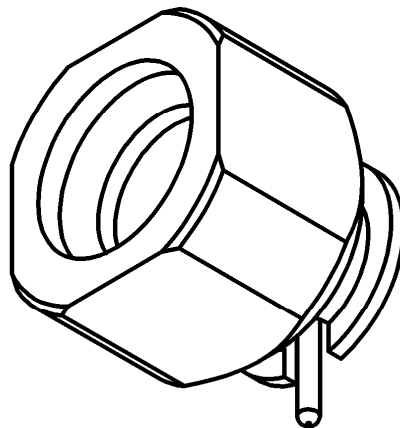
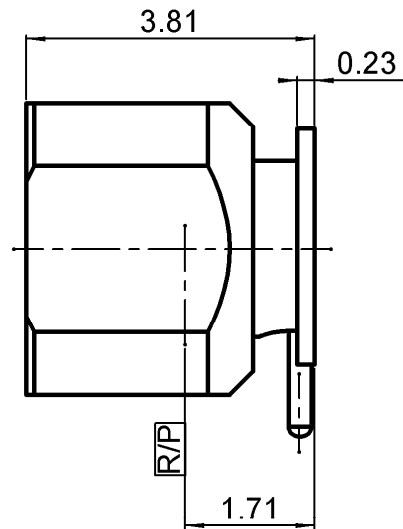
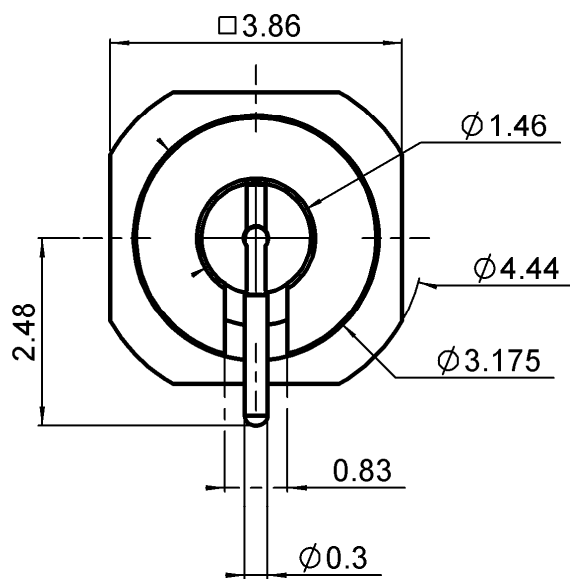


SMT PLUG RECEPTACLE

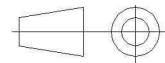
SMOOTH BORE

R201.508.700

Series : SMPM



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY	BERYLLIUM COPPER	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PEEK	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 1345 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

RADIAL 

SMT PLUG RECEPTACLE**SMOOTH BORE****R201.508.700**

Series : SMPM

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-20	GHz
VSWR	** + 0,0000	x F(GHz) Maxi
Insertion loss	0.12	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini

ENVIRONMENTAL

Operating temperature	-65/+165	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :

** 1.15 to 12GHz

** 1.35 to 20GHz

*** after soldering on PCB

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	6.7***	N mini
Axial force – Opposite end	6.7***	N mini
Torque	NA	N.cm mini

Recommended torque

Mating	NA	N.cm
Panel nut	NA	N.cm

Mating life	500	Cycles mini
Weight	0,2700	g

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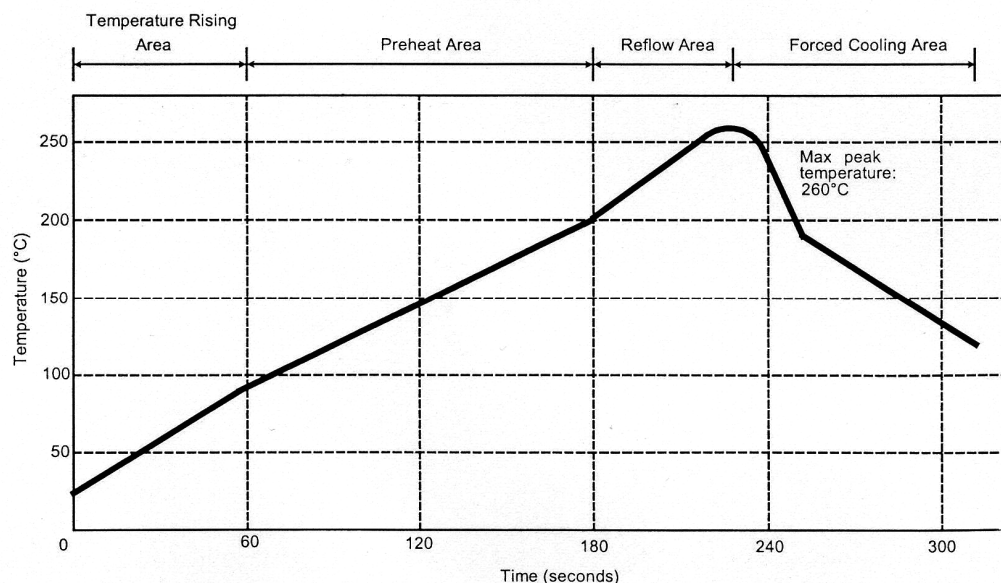

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SMT PLUG RECEPTACLE**SMOOTH BORE****R201.508.700**

Series : SMPM

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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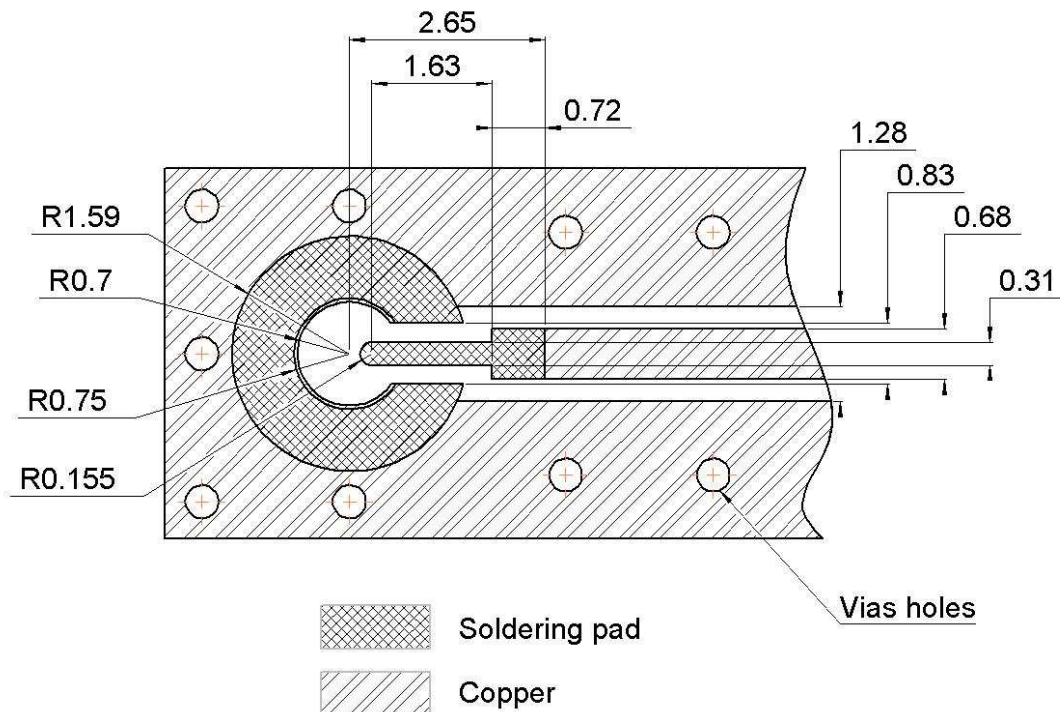
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SMT PLUG RECEPTACLE**SMOOTH BORE****R201.508.700**

Series : SMPM

RECOMMENDED PAD DIMENSIONS

Substrat: RT5880 thickness 0.254 mm, with copper layer 35µm on both sides.
Add vias between both sides along upper ground plane according to engineering practise.

**Issue : 1345** A

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